# CRMKGH0403A

### N-Channel 40V, 3.5mΩ Typ. Power MOSFET

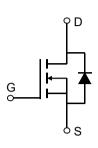
# **Description**

### **Features**

• 40V, 80A

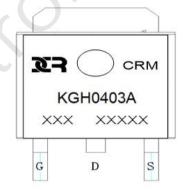
 $R_{DS(ON)}$  Typ = 3.5m $\Omega$  @  $V_{GS}$  = 10V

- Advanced Split Gate Trench Technology
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



### Schematic Diagram

# G S



**Marking and Pin Assignment** 

# **Application**

- Load Switch
- PWM Application
- Power Management

# **Package Marking and Ordering Information**

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGH0403A	CRMKGH0403A	TO-252-3L	TAPING	13"	2500	25000

# **Absolute Maximum Ratings** (@ $T_J = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		40	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T <sub>C</sub> = 25°C	80	Α
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 100°C	48	Α
I <sub>DM</sub>	Pulsed Drain Current (1)		320	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		81	mJ
$P_{D}$	Power Dissipation	T <sub>C</sub> = 25°C	52	W
$R_{ hetaJC}$	Thermal Resistance, Junction to Case		2.4	°C/W
$T_J,T_STG$	Junction & Storage Temperature Range		-55 to 150	°C



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# **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 40V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	3	3.6	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10V, I_D = 30A$	-	3.5	4.6	mΩ
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance		- /	1402	-	pF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 20V,$ f = 1MHz	-	476	-	pF
$C_{rss}$	Reverse Transfer Capacitance	1 - 1101112	X - \	40	-	pF
Q <sub>g</sub>	Total Gate Charge		-	27	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 20V, I_{D} = 20A$	<b>)</b> .	6	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V <sub>DS</sub> - 20V, I <sub>D</sub> - 20A	-	5	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	9.5	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 20V$	-	9.5	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D$ = 20A, $R_{GEN}$ = $3\Omega$	-	20	-	ns
$t_{f}$	Turn-Off Fall Time		-	7.5	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	80	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	320	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I 00A 1771 400A7	-	23	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20A$ , di/dt = 100A/us	-	20	_	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup>  $E_{AS}$  condition: Starting  $T_J$ =25°C,  $V_{DD}$ =20V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =18A

<sup>3.</sup> Pulse Test: Pulse Width  $\!\!\leqslant\! 300\mu s,$  Duty Cycle  $\!\!\leqslant\! 0.5\%.$ 

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# **Test Circuit**

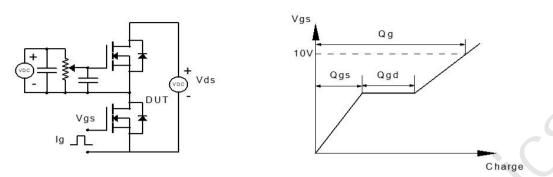


Figure 1: Gate Charge Test Circuit & Waveform

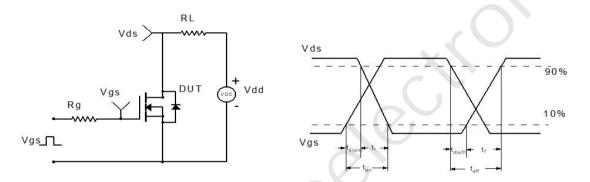


Figure 2: Resistive Switching Test Circuit & Waveform

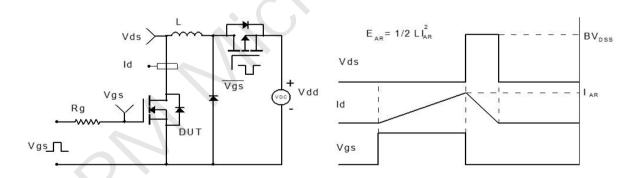


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

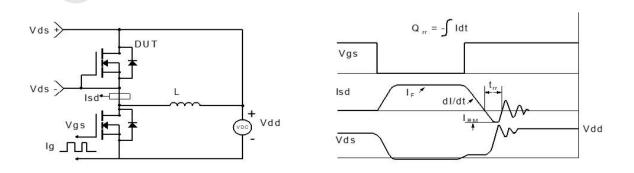
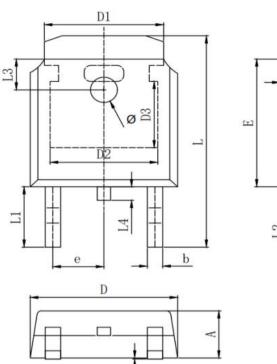


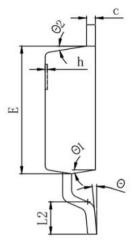
Figure 4: Diode Recovery Test Circuit & Waveform

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# Package Mechanical Data(TO-252-3L)





SYMBOL	MILLIMETER				
SIMBUL	MIN	Typ.	MAX		
A	2.200	2. 300	2.400		
A1	0.000		0. 127		
b	0.640	0.690	0.740		
(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6. 700		
D1	5. 334 REF				
D2	4. 826 REF				
D3	3. 166 REF				
E	6.000	6. 100	6. 200		
e	2. 286 TYP				
h	0.000	0.100	0. 200		
L	9. 900	10.100	10.300		
L1	2. 888 REF				
L2	1.400	1.550	1.700		
L3	1.600 REF				
L4	0.600	0.800	1.000		
ф	1.100	1.200	1.300		
θ	0°		8°		
θ 1	9° TYP				
θ2	9° TYP				

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# **Contact information**

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